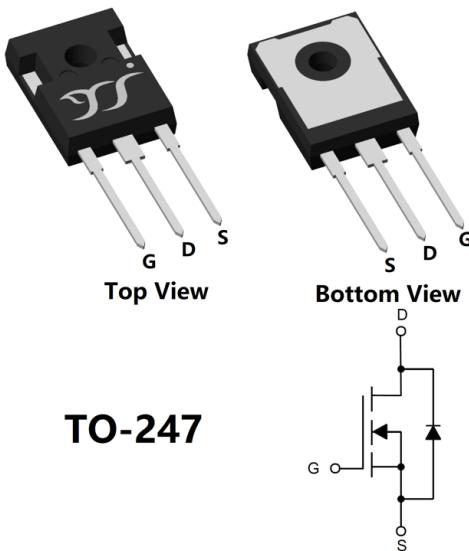




## N-Channel Enhancement Mode Field Effect Transistor



### Product Summary

- $V_{DS}$  600V
- $I_D$  102A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ )  $<18.5m\Omega$
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- EV Charger
- AC-DC Power Management
- Server/Telecom/PC Power

### ■ Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit
Drain-source Voltage			$V_{DS}$	-	600	V
Gate-source Voltage			$V_{GS}$	-20	20	
Continuous Drain Current (Note 1,2)	Steady-State	$T_A=25^\circ C, V_{GS}=10V$	$I_D$	-	8.2	A
		$T_A=100^\circ C, V_{GS}=10V$		-	5.2	
Continuous Drain Current (Note 1,3)		$T_C=25^\circ C, V_{GS}=10V$ , Chip limitation		-	102	
		$T_C=100^\circ C, V_{GS}=10V$		-	64.5	
Pulsed Drain Current	$T_C=25^\circ C, t_p \leq 10\mu s$		$I_{DM}$	-	408	
Maximum Body-Diode Continuous Current	$T_C=25^\circ C$		$I_S$		102	
Maximum Body-Diode Pulsed Current	$T_C=25^\circ C, t_p \leq 10\mu s$		$I_{SM}$	-	408	
Avalanche energy (non-repetitive)	$T_J=25^\circ C, V_G=10V, R_G=25\Omega, L=30mH, IAS=12A$		EAS	-	2160	mJ
Total Power Dissipation (Note 1,2)	Steady-State	$T_A=25^\circ C$	$P_D$	-	3.1	W
		$T_A=100^\circ C$		-	1.2	
Total Power Dissipation (Note 1,3)	Steady-State	$T_C=25^\circ C$		-	480	
		$T_C=100^\circ C$		-	192	
MOSFET dv/dt ruggedness	$V_{DS}=0...300V, R_g=0\Omega$		dv/dt	-	50	V/ns
Reverse diode dv/dt	$V_{DS}=0...300V, I_D \leq 100A, di/dt=200A/\mu s$		dv/dt	-	28	
Maximum diode commutation speed	$V_{DS}=0...300V, I_D \leq 100A, R_g=0\Omega$		dif/dt	-	6940	A/ $\mu s$
Junction and Storage Temperature Range			$T_J, T_{STG}$	-55	150	°C

### ■ Thermal resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	$R_{\theta JA}$	-	40	°C/W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	0.26	

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJW018C60CF	B1	YJW018C60CF	30	360	1800	Tube



## ■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 1mA, T_j = 25^\circ C$	600	-	-	V
		$V_{GS} = 0V, I_D = 30mA, T_j = 25^\circ C$	600	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 600V, V_{GS} = 0V, T_j = 25^\circ C$	-	-	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V, T_j = 25^\circ C$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1mA, T_j = 25^\circ C$	3	-	5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 58A, T_j = 25^\circ C$	-	15.5	18.5	$m\Omega$
		$V_{GS} = 10V, I_D = 58A, T_j = 150^\circ C$	-	38.64	46.12	
Diode Forward Voltage	$V_{SD}$	$I_S = 58A, V_{GS} = 0V, T_j = 25^\circ C$	-	0.99	1.3	V
Gate resistance	$R_G$	$f = 1MHz, T_j = 25^\circ C$	-	0.9	-	$\Omega$
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 300V, V_{GS} = 0V, f = 1MHz, T_j = 25^\circ C$	-	11085	-	pF
Output Capacitance	$C_{oss}$		-	190	-	
Reverse Transfer Capacitance	$C_{rss}$		-	10	-	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{DS} = 0...300V, V_{GS} = 0V, f = 1MHz, T_j = 25^\circ C$	-	546	-	
Effective output capacitance, time related	$C_{o(tr)}$		-	5340	-	
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS} = 10V, V_{DS} = 300V, I_D = 58A, T_j = 25^\circ C$	-	278.3	-	nC
Gate-Source Charge	$Q_{gs}$		-	69.5	-	
Gate-Drain Charge	$Q_{gd}$		-	132.7	-	
Reverse Recovery Charge	$Q_{rr}$	$I_F = 58A, dI/dt = 100A/us, V_{GS} = 0V, V_R = 300V, T_j = 25^\circ C$	-	1588	-	nC
Reverse Recovery Time	$t_{rr}$		-	200	-	ns
Peak Reverse Recovery Current	$I_{rrm}$		-	12	-	A
Turn-on Delay Time	$t_{D(on)}$	$V_{GS} = 10V, V_{DS} = 300V, I_D = 58A, R_{GEN} = 3\Omega, T_j = 25^\circ C$	-	140	-	ns
Turn-on Rise Time	$t_r$		-	32	-	
Turn-off Delay Time	$t_{D(off)}$		-	137	-	
Turn-off fall Time	$t_f$		-	6.5	-	

### Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of  $R_{\theta JA}$  is measured in the still air environment with  $T_A = 25^\circ C$ . The maximum allowed junction temperature of  $150^\circ C$ .
- Thermal resistance from junction to soldering point (on the exposed drain pad)

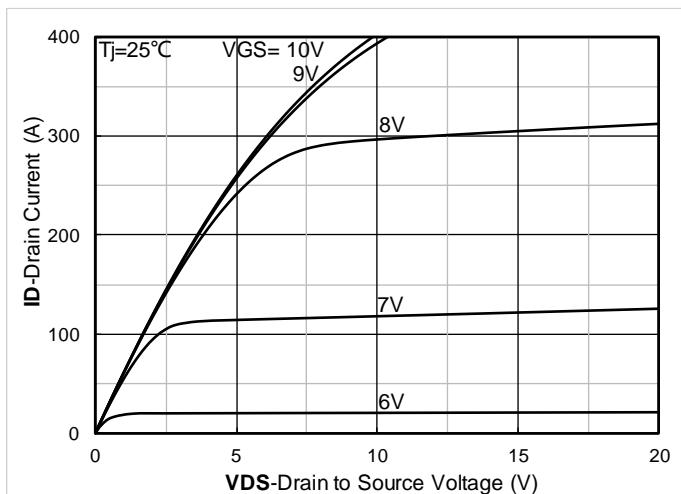
**■Typical Electrical and Thermal Characteristics Diagrams**

Figure 1. Output Characteristics; typical values

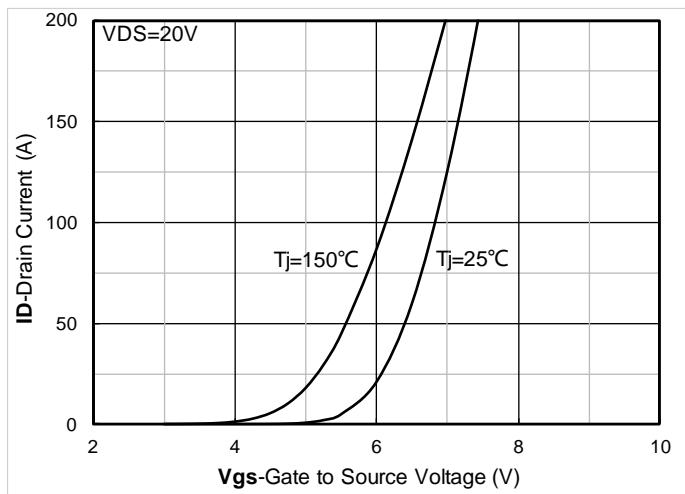


Figure 2. Transfer Characteristics; typical values

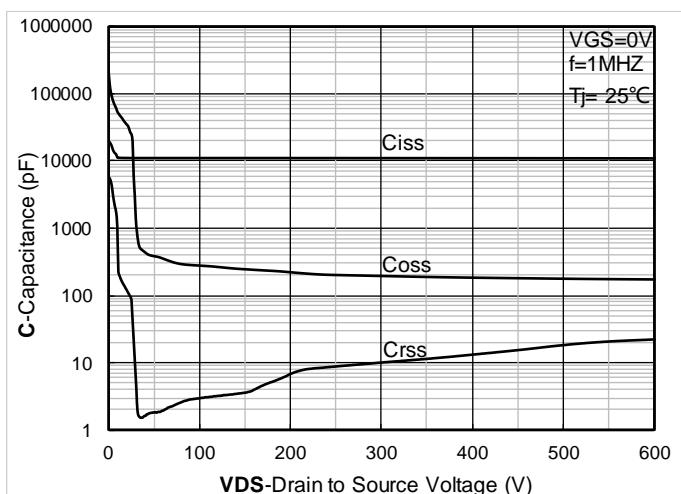


Figure 3. Capacitance Characteristics; typical values

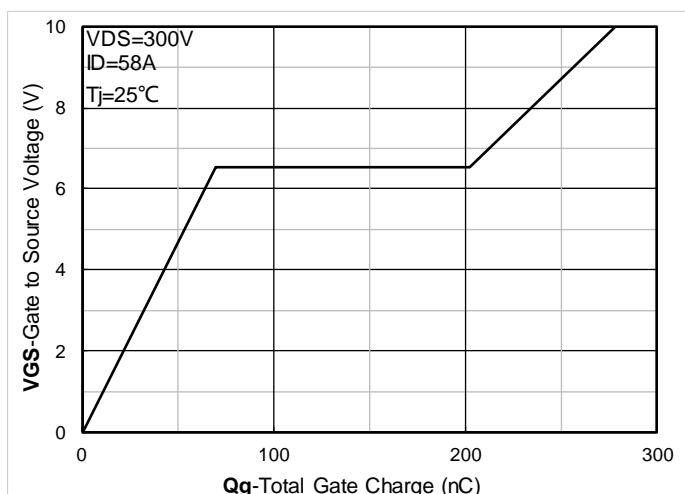


Figure 4. Gate Charge; typical values

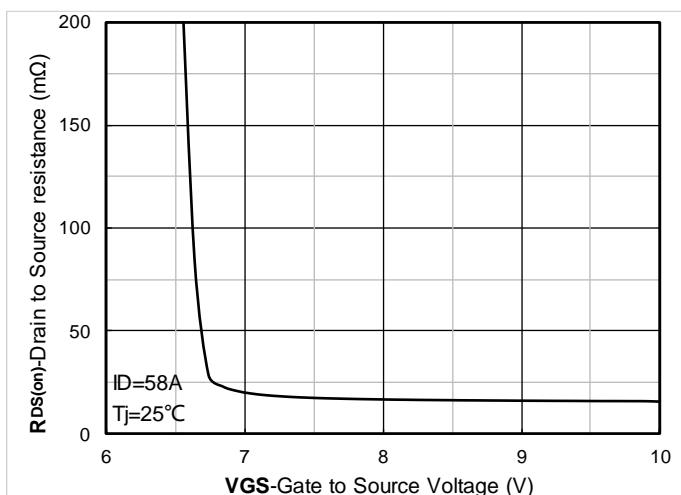


Figure 5. On-Resistance vs Gate to Source Voltage; typical values

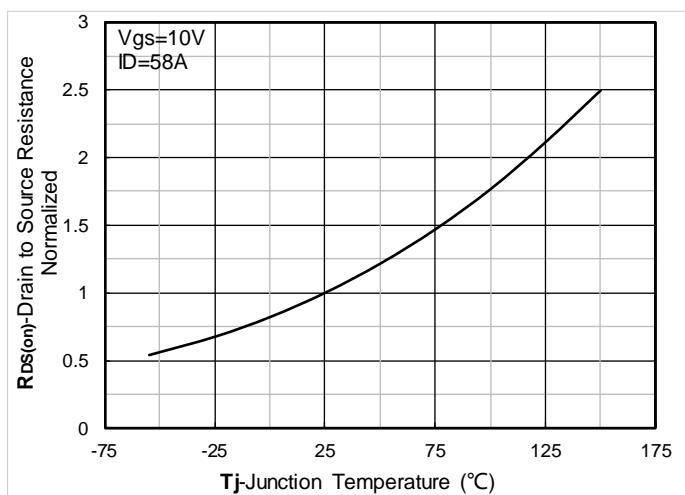


Figure 6. Normalized On-Resistance



**YJW018C60CF**

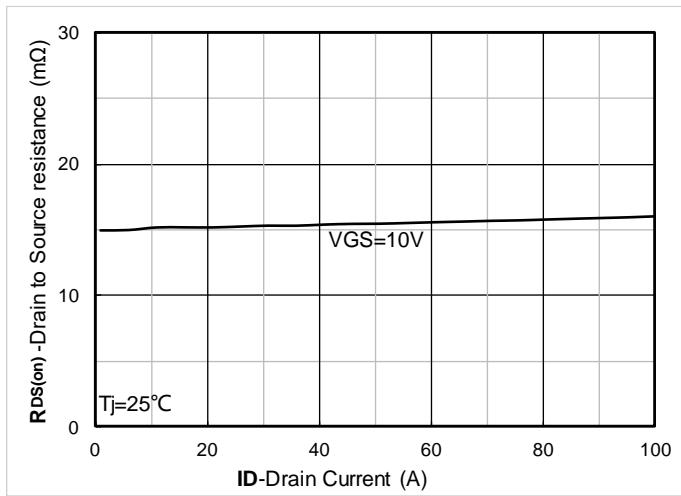


Figure 7.  $R_{DS(on)}$  VS Drain Current; typical values

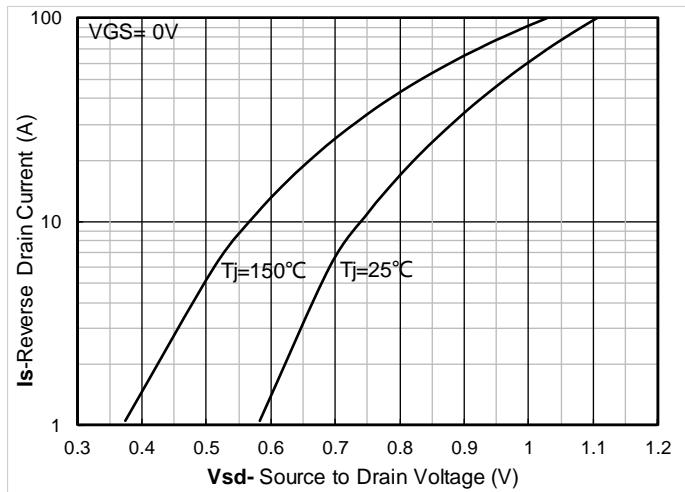


Figure 8. Forward characteristics of reverse diode; typical values

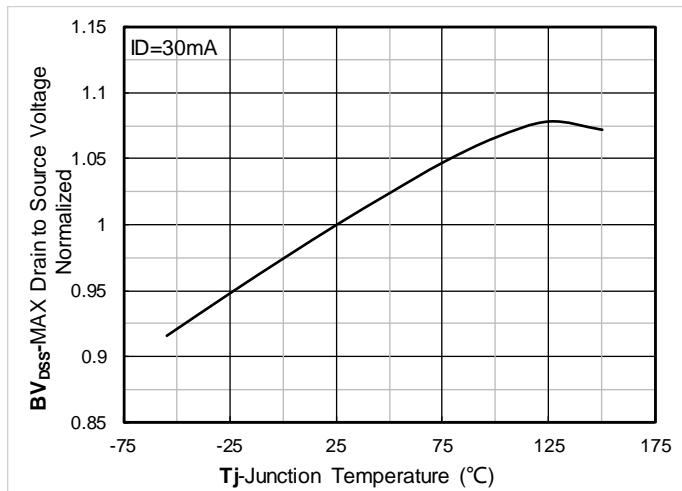


Figure 9. Normalized breakdown voltage

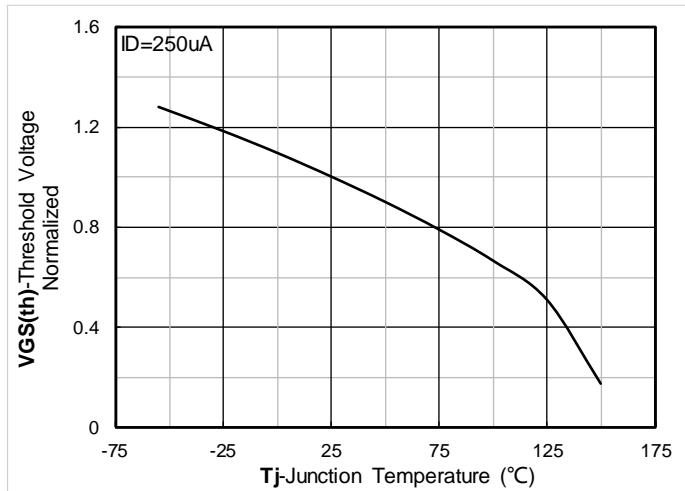


Figure 10. Normalized Threshold voltage

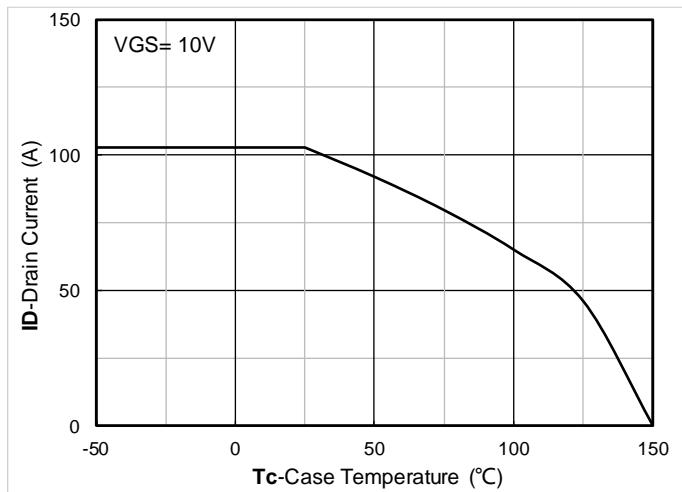


Figure 11. Current dissipation

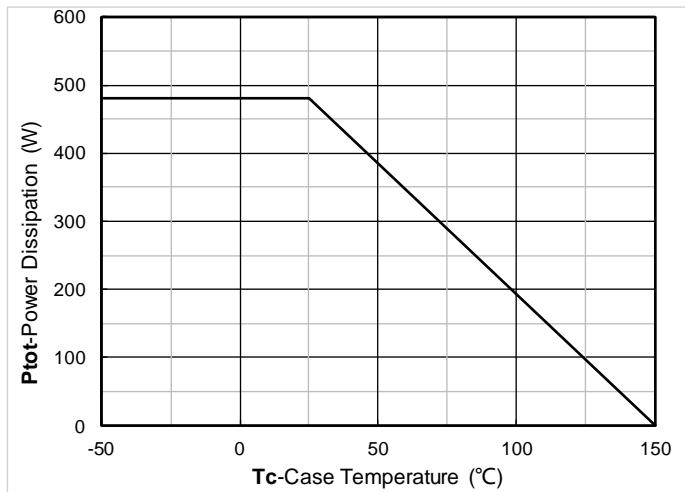


Figure 12. Power dissipation

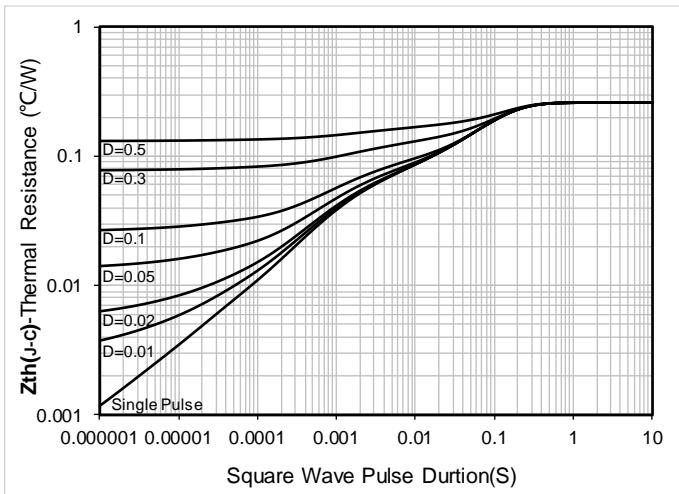


Figure 13. Maximum Transient Thermal Impedance

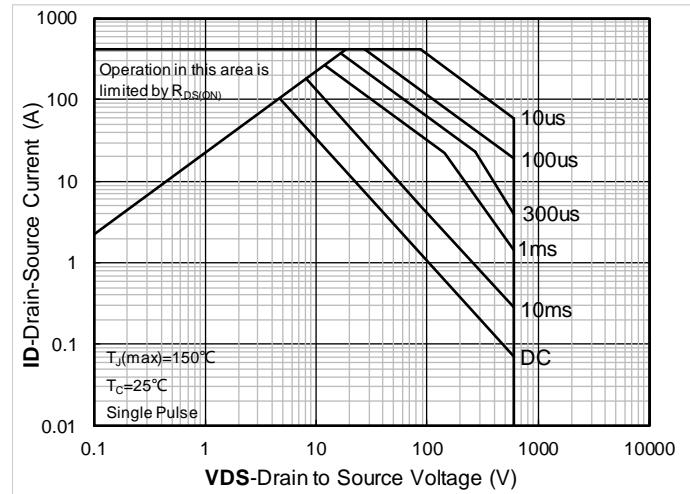


Figure 14. Safe Operation Area

## ■ Test Circuits & Waveforms

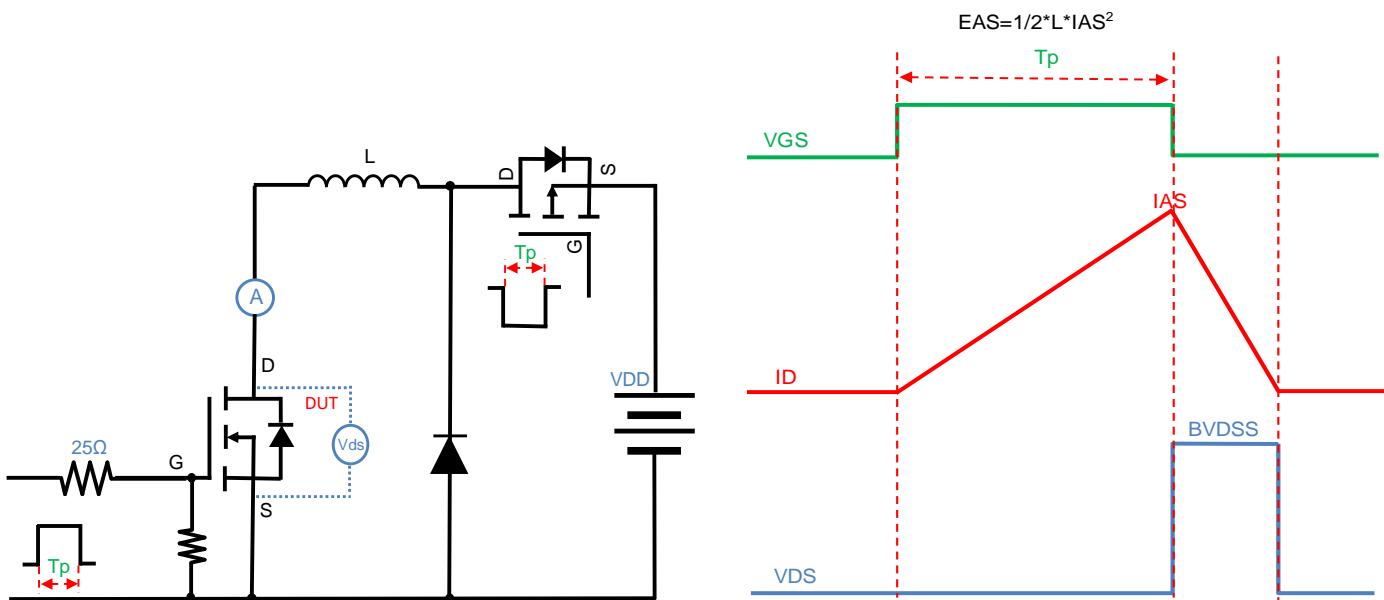


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

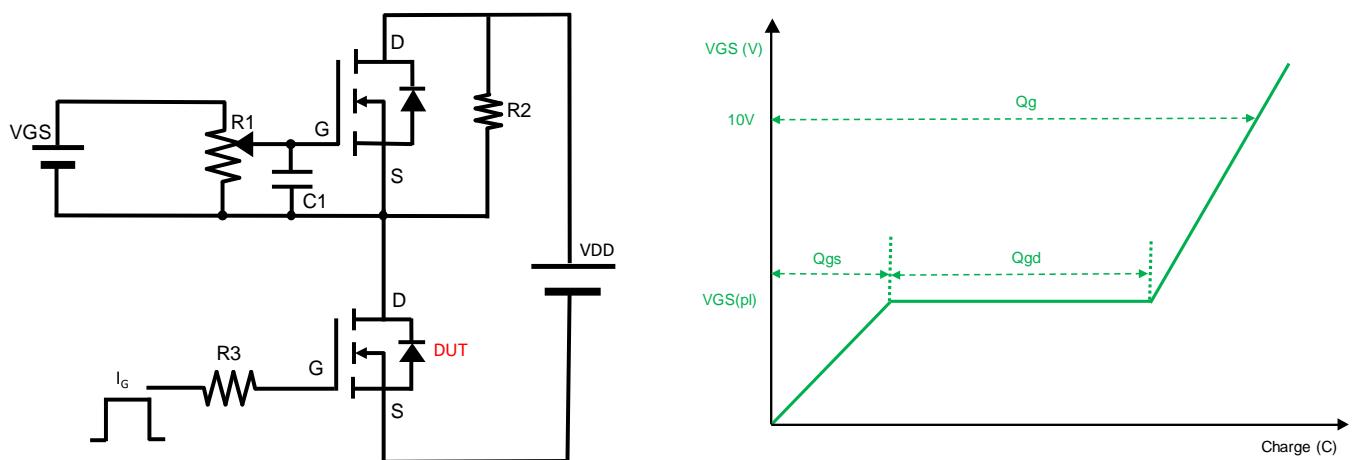


Figure B. Gate Charge Test Circuit & Waveform

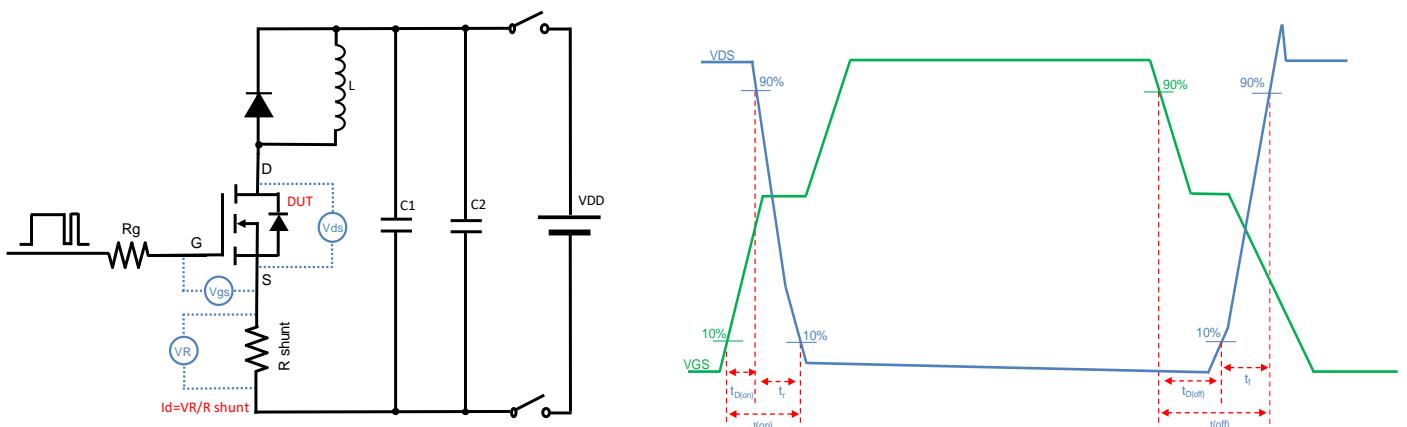


Figure C. Resistive Switching Test Circuit & Waveform

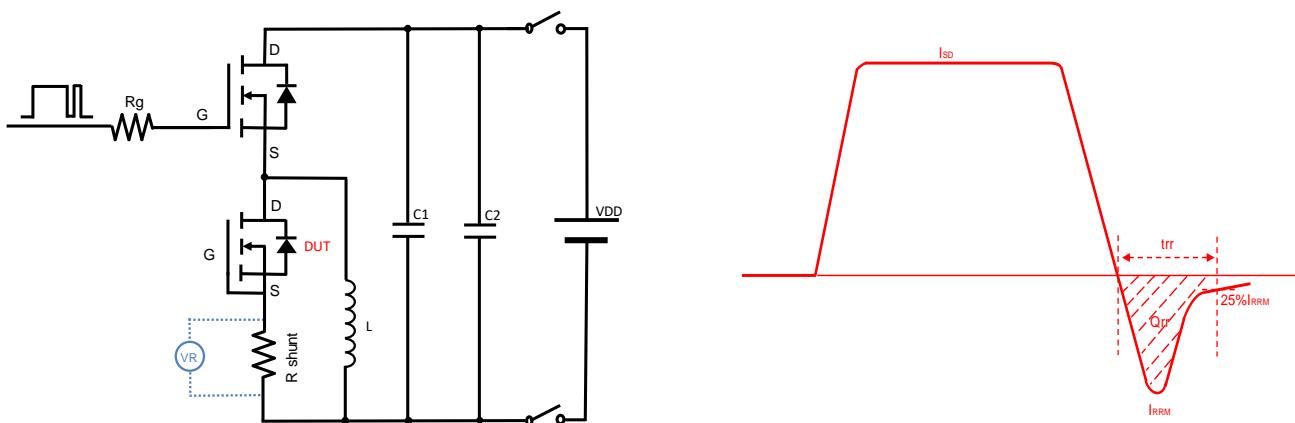
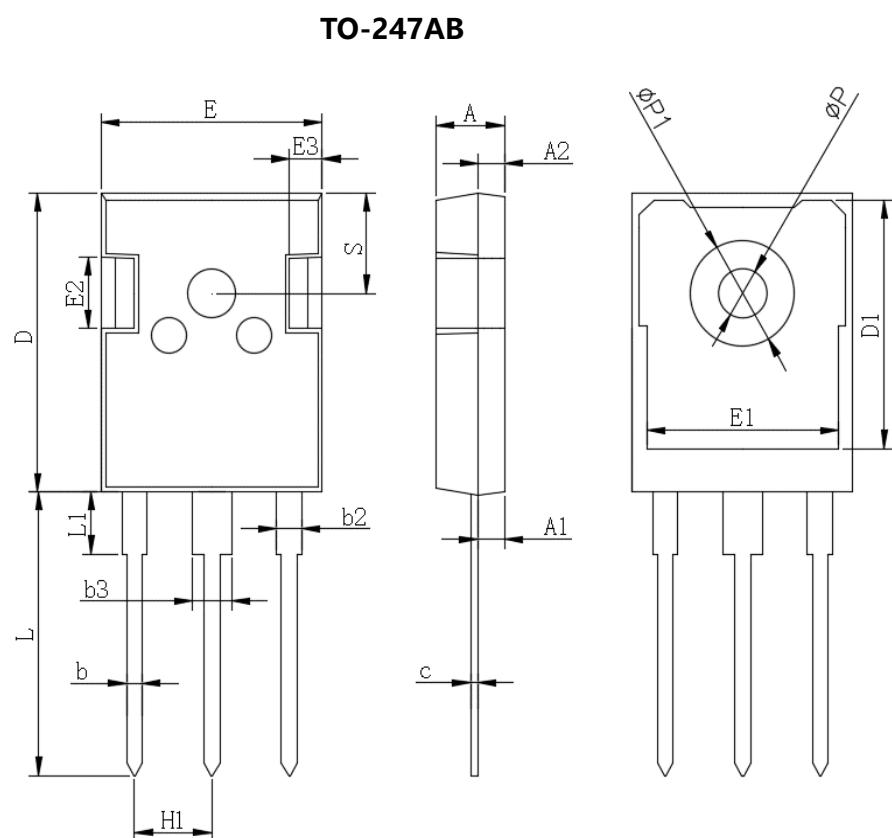


Figure D. Diode Recovery Test Circuit & Waveform



## ■ TO-247AB Package information



TO-247AB		
Dim	Min	Max
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.0	1.4
b2	1.91	2.21
c	0.5	0.7
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.0	13.6
E2	4.80	5.20
E3	2.30	2.70
L	19.62	20.22
L1	-	4.30
$\phi P$	3.40	3.80
$\phi P_1$	-	7.30
S	6.15TYP	
H1	5.44TYP	
b3	2.80	3.20



## Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.21yangjie.com>, or consult your nearest Yangjie's sales office for further assistance.